PWM Control Type
DC/DC Converter IC for AC/DC Driver

BD7679G

●General Description

BD7679G is a PWM controller type DC/DC converter IC for AC/DC that provides an optimum system for all products that requires an electrical outlet. This product supports both isolated and non-isolated devices. IC enables simple design of low-power electrical converters. With switching MOSFET and current detection resistor as external devices, it enables more freedom in design.
Since the peak current control is utilized, peak current is controlled in each cycles, application excels wide bandwidth and transient response.

BD7679G includes various protective functions such as soft start function, burst function, per-cycle over current limiter, VCC overvoltage protection and overload protection.

An external stop pin (COMP pin) is provided, so that switching stopping can be set by external signals. The function is available as overheating protection and over voltage protection of secondary output, so on.
The PWM switching frequency is fixed at 65 kHz.
A frequency hopping function is included which contributes to low EMI.

●Features

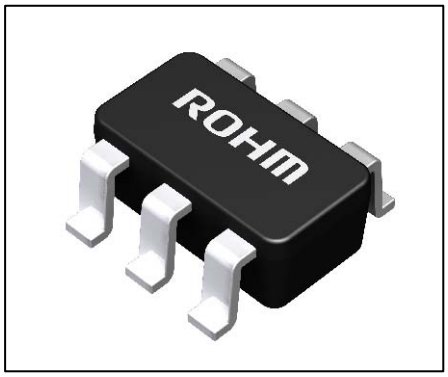
- PWM frequency of 65kHz
- PWM current mode method
- Low circuit current when UVLO is ON (12μA at VCC=12V)
- Low circuit current without load (Burst operation when load is light)
- Built-in SW frequency hopping function
- 250ns leading-edge blanking
- VCC UVLO / OVP (Auto restart)
- Per-cycle over current protection circuit
- Soft start
- Output overload protection(Auto-restart protection)
- External stop function for COMP pin (Auto restart)

●Key Specifications

- Power Supply Voltage range: 8.5V to 25.0V
- Operating Current: Normal: 0.60mA (Typ)
  Burst: 0.40mA (Typ)
- Oscillation Frequency: 65kHz (Typ)
- Operating Temperature range: -40°C to +85°C

●Package

	W(Typ) x D (Typ) x H (Max)
SSOP6	2.90mm x 2.80mm x1.25mm



●Applications

AC adapters and household appliances (vacuum cleaners, humidifiers, air cleaners, air conditioners, refrigerators, IH cooking heaters, rice cookers, etc.)

●Typical Application Circuit

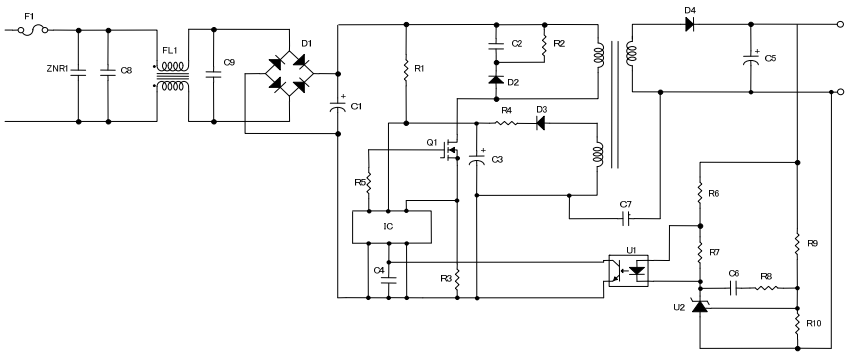


Figure 1, Application Diagram (Isolated type)

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●Pin Configuration（SSOP6）

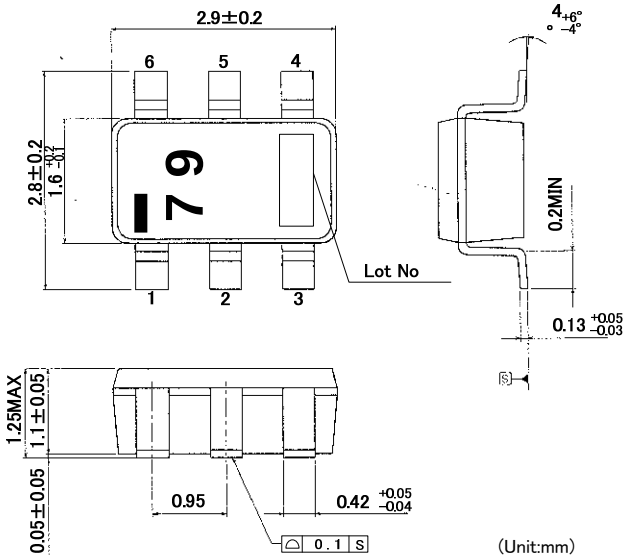


Figure 2, External Dimensions of SSOP6 Package

●Pin Description

Table 1 I/O PIN Functions

NO.	Pin Name	I/O	Function	ESD protection system	
				VCC	GND
1	GND	I/O	GND pin	○	-
2	FB	I	Feedback signal input pin	○	○
3	COMP	I	Comparator input pin	○	○
4	CS	I	Primary current sensor pin	○	○
5	VCC	I	Power supply input pin	-	○
6	OUT	O	External MOS drive pin	○	○

●I/O Equivalent Circuit

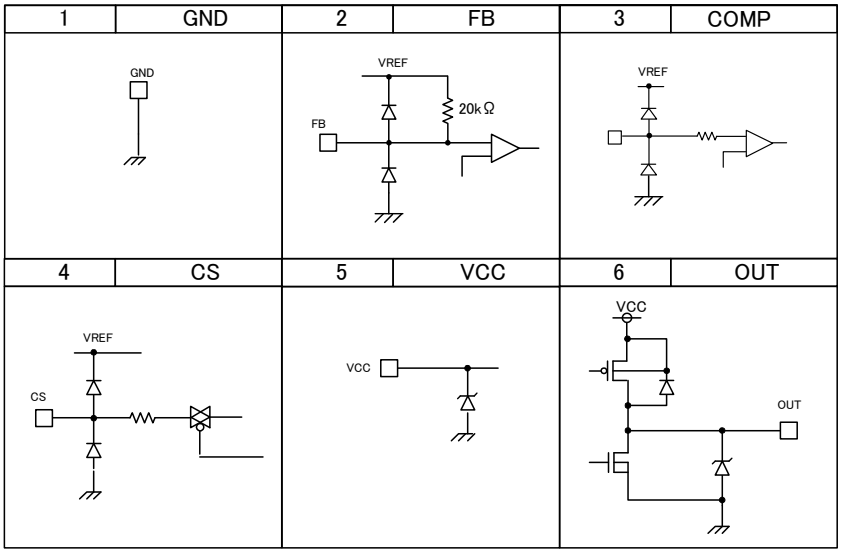


Figure 3, I/O Equivalent Circuit

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●Block Diagram

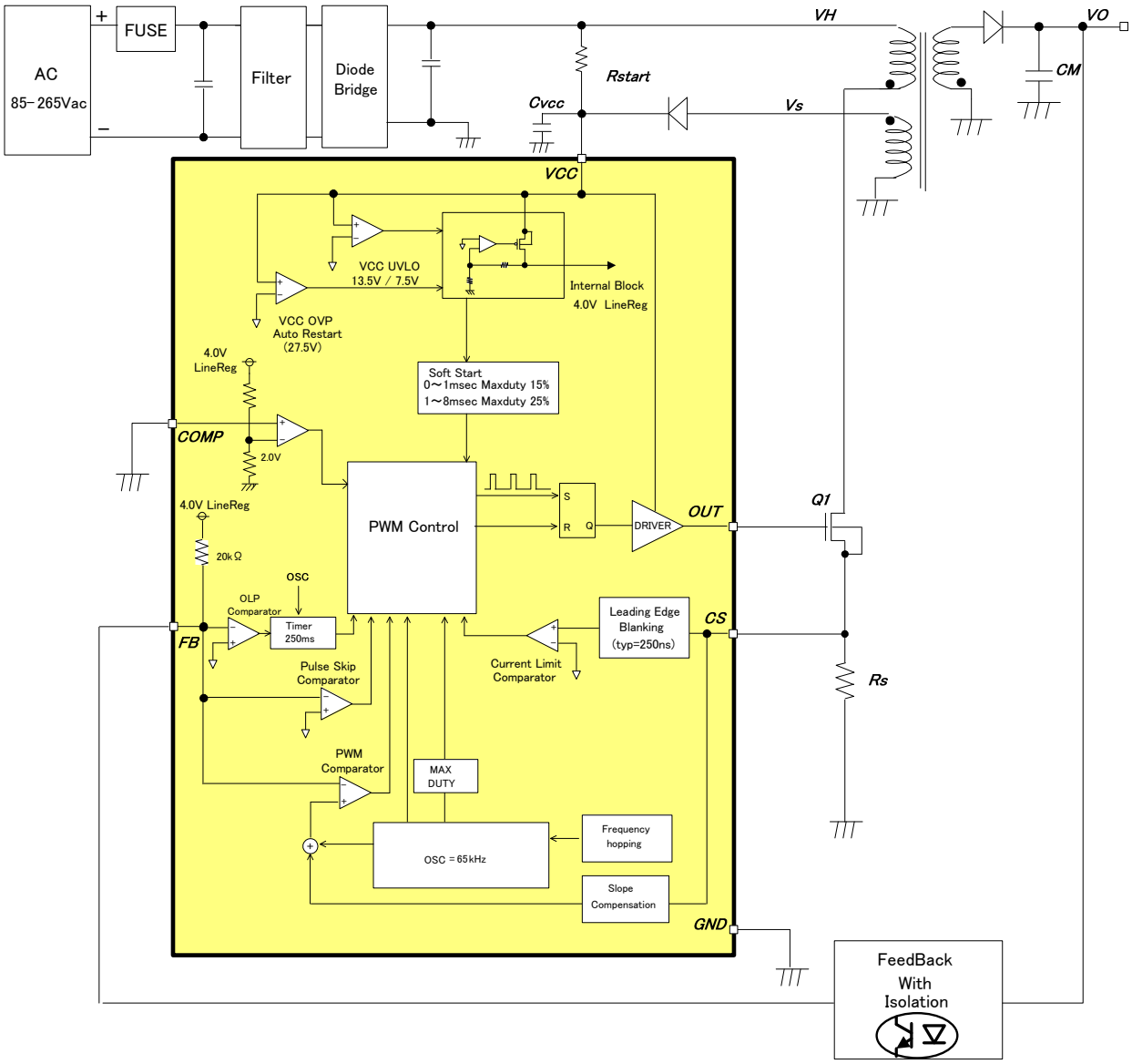


Figure 4, Block Diagram

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●Description of Each Block

(1) Start Sequences (Soft Start Operation, Light Load Operation, and Overload Protection)

Start sequences are shown in Figure 5. This is also shown the operation of overload protection.
See the sections below for detailed descriptions

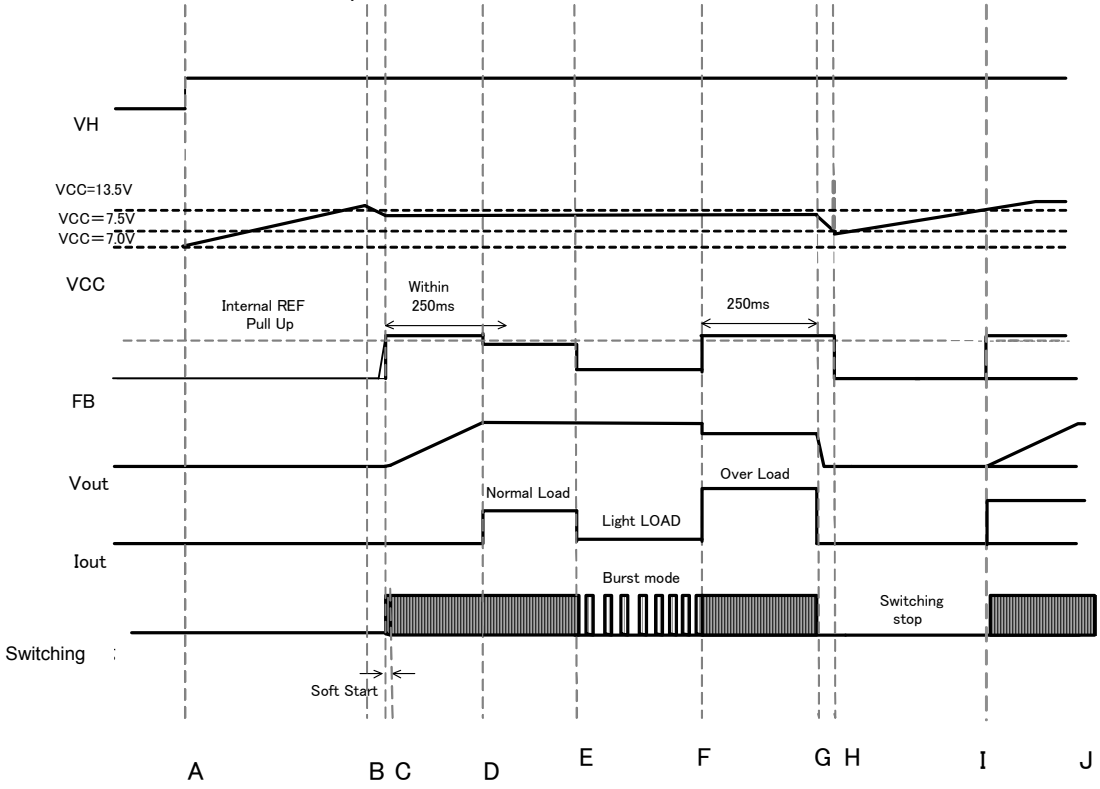


Figure 5, Start Sequence Timing Chart

A: Input voltage VH is applied

B: VCC pin voltage rises by being supplied from VH line through start resistor “Rstart” and the IC starts operating when VCC > V_{UVLO1} (13.5V Typ).
Switching operation starts when other protection functions are judged as normal.
From startup to be stable output voltage, application should be set to stabilize output voltage during VCC > V_{UVLO2} (7.5V Typ) because the VCC pin consumption current causes the VCC voltage drop.

C: Operated soft start function, maximum duty is restricted to 15% during a 1ms period to prevent any excessive rise in voltage or current. From 1ms to 8ms, maximum duty is restricted to 25%. Maximum duty is restricted to 75% after 8ms.

D: VOUT voltage rises when the switching operation starts.
Once the output voltage starts, it is set to the rated voltage level within the T_{FOLP} period (250ms Typ).
The output voltage is regulated within T_{FOLP} (=250ms Typ) from starting.

E: During Light Load, when FB pin voltage < V_{BST} (=0.3V Typ), Burst method is operated to keep power consumption down.

F: Over Load condition occurs when FB pin voltage > V_{FOLP1A} (=3.6V Typ).

G: When FB pin voltage is at V_{FOLP1A} (= 3.6V Typ) for more than T_{FOLP} (250ms Typ), the overload protection function is triggered and switching is stopped. The IC’s internal 250ms timer is reset during the T_{FOLP} period (250ms Typ) if FB < V_{FOLP1B} even once.

H: If the VCC voltage drops to V_{UVLO2} (7.5Vtyp) or below, restart is executed.

I: The IC’s circuit current is reduced and the VCC pin value rises. (Same as B).

J: Same as D

In Figure 4, start resistor Rstart is needed to start the application.
When the start resistor Rstart value is reduced, standby power is increased and the startup time is shortened.
Conversely, when the start resistor Rstart value is increased, standby power is reduced and the startup time is lengthened.
Standby current is less than 20uA at VCC UVLO is disable, and it can calculate VCC UVLO voltage from V_{UVLO1}=14.5V (Max).

ex） Starting resistor Rstart setting method;

$$Rstart = (VHmin - V_{UVLO1}（Max）) / I_{OFF}（Max）$$

In the case of Vac=100V (-20% of a margin), Rstart requirement can be found by the following formulas:

$$VHmin = 100 \times \sqrt{2} \times 0.8 = 113V$$

Because of V_{UVLO1} (Max) =14.5V, Rstart ≦ (113V - 14.5V) / 20μA＝4.975MΩ

Start-up time can be found by the following formulas:

$$Tstart = -Rstart \times C_{VCC} \times \ln (1-V_{UVLO1}/VHmin)$$

ex） Rstart=3.0MΩ

Rstart resistor loss in this case is : $Pd (Rstart) = (VH-VCC)^2 / Rstart = (141V - 14.5V)^2 / 3.0M = 5.35mW$.

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(2) VCC Pin Protection

BD7679G includes UVLO (Under Voltage Locked Out) and OVP (Over Voltage Protection) functions to monitor VCC pin voltage (see Figure 6 for OVP auto-restart operation).
The UVLO function prevents damage to MOSFET by stopping switching operations when the VCC pin voltage drops to VCC < V_{UVLO2} (= 7.5V Typ).
The VCC OVP function prevents damage to MOSFET by stopping switching operations when the VCC pin voltage exceeds V_{OVP1} (= 27.5V Typ). Once the switching is stopped, IC stops switching until VCC < V_{OVP2}(=22.5V Typ).
A blanking time of T_{STOP}(=100us.Typ) is prepared for protecting mal-function.

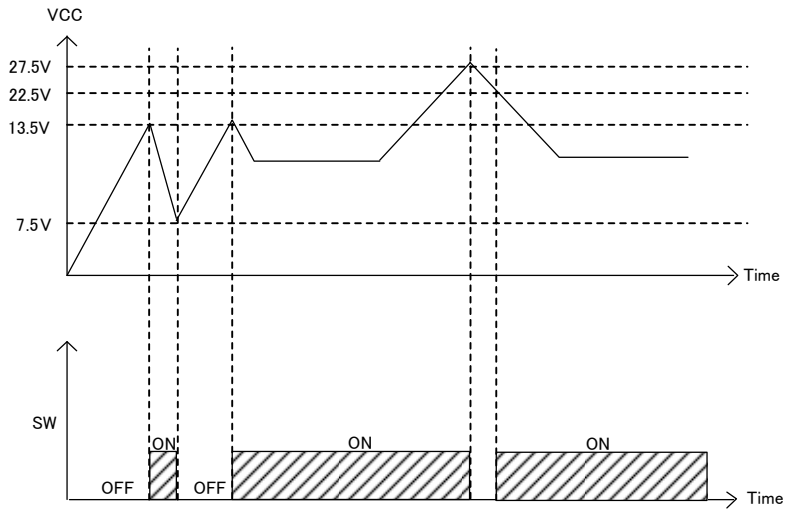


Figure 6, VCC UVLO/OVP Operation (Auto-restart)

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(3) DCDC Driver (PWM Comparator, Frequency Hopping, Slope Compensation, OSC, Burst)

BD7672BG uses current mode PWM control. In the internal generator, the average switching frequency is 65 kHz. Furthermore, switching frequency hopping function is built-in while the switching frequency fluctuation is shown as in Figure 7. Fluctuation cycle is 125Hz (=8ms).

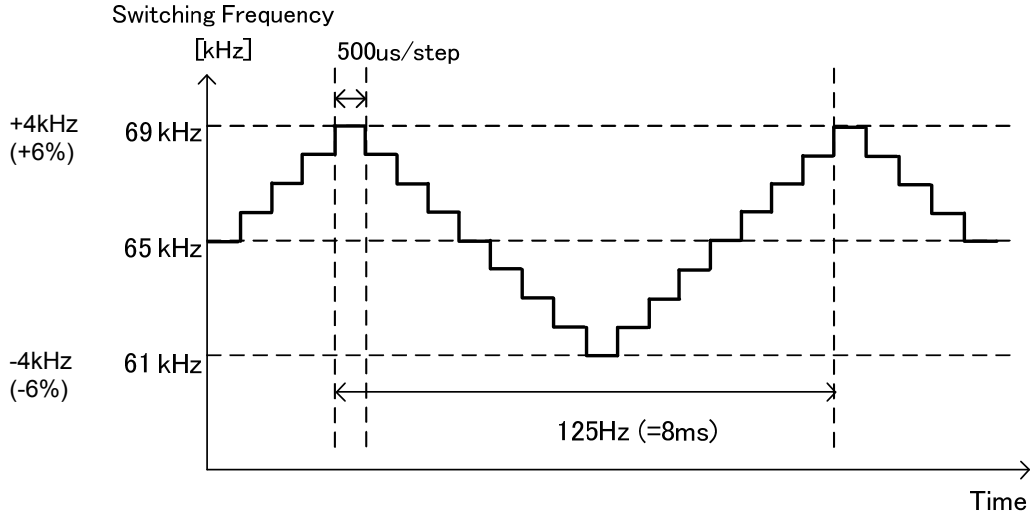


Figure 7, Frequency Hopping Function

The max-duty cycle is fix to 75% (Typ) at OUT pin and minimum pulse width is fix at 500ns (Typ). When the duty cycle exceeds 50% at Current Mode control, the sub-harmonic oscillation occurs. To prevent it, IC is built-in slope compensation function.

BD7672BG has burst mode function to attain less power consumption when load is light. This function monitors FB pin voltage and detects light load when FB voltage < VBST (=0.3V Typ).

The secondary output voltage, the FB voltage and the DCDC function are shown in Figure 8.

FB pin is pulled up by R_{FB} (=20kΩ Typ). At light load, when the secondary output voltage rises, the FB pin voltage will drop and when this goes below V_{BST} (=0.3V Typ) burst function will follow to reduce the power consumption.

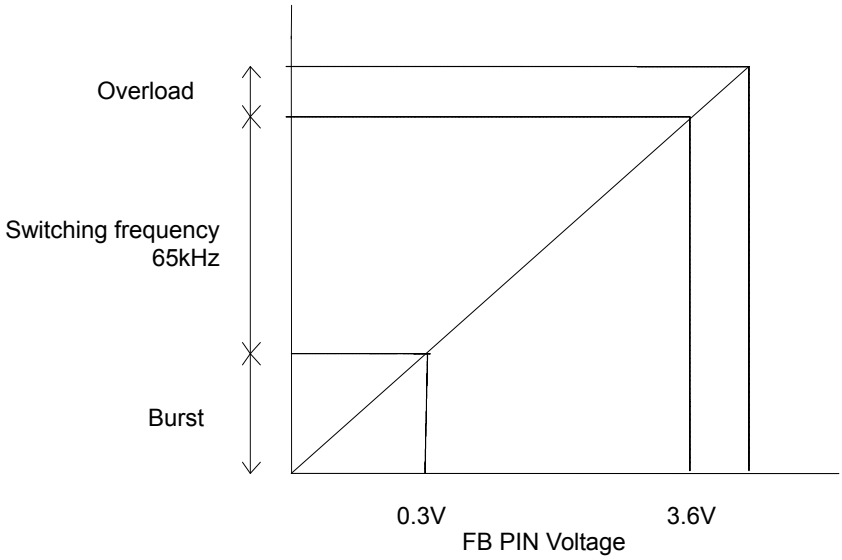


Figure 8, Switching Operation Status Changes by FB Pin Voltage

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(4) Over Current Limiter and Leading Edge Blanking Period

BD7679G has over current limiter for each switching cycle.
When the CS pin voltage exceeds the V_{CS} voltage (=0.5V Typ), switching is turned OFF.

In addition, when the driver MOSFET is turned ON, surge current occurs at each capacitor component and drive current. Therefore, when the CS pin voltage rises temporarily, the detection errors may occur in the over current limiter circuit. To prevent detection errors, the OUT pin is switched from low to high and the CS signal is blanked for 250nsec by the LEB (Leading Edge Blanking) function. This blanking function enables a reduction of CS pin noise filtering in response to noise that occurs when the OUT pin is switched from low to high.

(5) Output Overload Protection Function (FB OLP Comparator)

Overload Protection Function monitors the load status of secondary output through FB pin and stops the switching of OUT pin during excessive load. In over load condition, there is no current in photo-coupler because output voltage decreases (drops) while FB pin voltage rises.
When FB pin voltage exceeds V_{FOLP1A} (=3.6V Typ) at T_{FOLP} (=250ms Typ) interval continuously, a load is excessive and OUT pin is fixed to L. The timer of overload protection is reset when FB pin drops further than V_{FOLP1B} (=3.4V Typ) within TFOLP (=250ms Typ) after exceeding V_{FOLP1A} (=3.6V Typ). Switching functions within this T_{FOLP} (=250ms Typ).
FB voltage, which is pulled up in resistance to IC internal voltage operates from V_{FOLP1A} (=3.6V Typ) or more at start-up. For this matter, set the start-up time of the secondary output voltage such that the FB voltage is always V_{FOLP1B} (=3.4V Typ) or less within T_{FOLP} (=250ms Typ) at start-up.

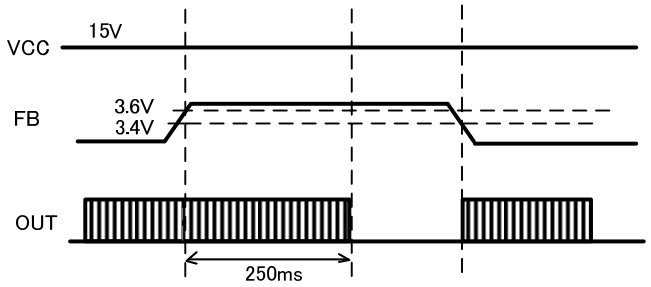


Figure 9, Overload Protection (Self-restart)

(6) COMP Pin External Stop Function

IC is stopped when the COMP pin voltage rises to V_{STOP1} (2.0V Typ). A masking timer for T_{STOP} (=100us Typ) prepared to prevent operation errors caused by noise.
Once IC stops by COMP stop function, IC stops until COMP < V_{STOP2}(=1.8V.Typ).

Overheating Protection by Posistor

When a posistor is attached to the COMP pin shown Figure-10, the switching operation can be stopped when overheating occurs.

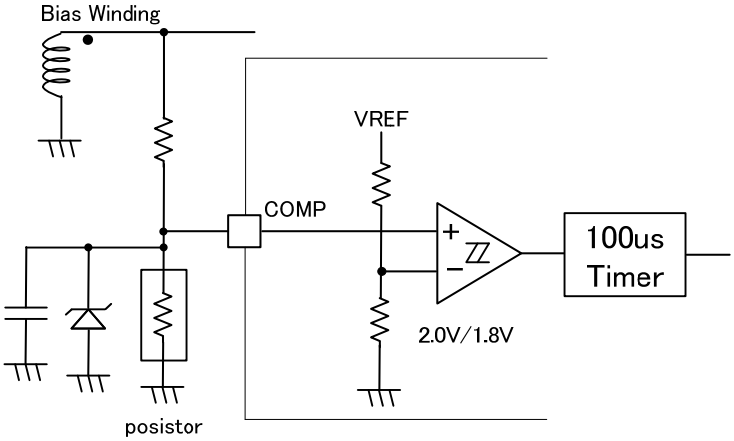


Figure 10 COMP Pin Overheating Protection Application

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●Absolute Maximum Ratings（Ta=25℃）

Parameter	Symbol	Rating	Unit	Conditions
Maximum Applied Voltage 1	Vmax1	30	V	VCC, OUT
Maximum Applied Voltage 2	Vmax2	6.5	V	CS, FB, COMP
OUT pin output Peak Current	I_{OUT}	±1.0	A	
Power Dissipation (Note1)	Pd	0.68 (Note1)	W	When implemented
Operating Temperature Range	Topr	-40 to +85	°C	
Storage Temperature Range	Tstr	-55 to +150	°C	

(Note1) SSOP6: Derate by 5.399 mW/°C when operating above Ta=25°C (when mounted on 70 mm × 70 mm, 1.6 mm thick, glass epoxy on single-layer substrate).

Caution: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

●Recommended Operating Ratings（Ta=25℃）

Parameter	Symbol	Rating	Unit	Conditions
Power Supply Voltage Range	VCC	8.5 to 26.0	V	VCC pin voltage

●Electrical Characteristics (Unless otherwise noted, Ta = 25°C, VCC=12V)

Parameter	Symbol	Specifications			Unit	Conditions
		MIN	TYP	MAX		
[Circuit Current]						
Circuit Current (OFF)	I_{OFF}	-	12	20	μA	VCC = 12V (UVLO = Detection)
Circuit Current (ON) 1	I_{ON1}	-	600	1000	μA	FB = 2.0V COMP: 100kΩ (during pulse operation)
Circuit Current (ON) 2	I_{ON2}	-	400	600	μA	FB = 0.0V COMP:100kΩ
[VCC Pin Protection Function]						
VCC UVLO Voltage 1	V_{UVLO1}	12.50	13.50	14.50	V	VCC rise
VCC UVLO Voltage 2	V_{UVLO2}	6.50	7.50	8.50	V	VCC drop
VCC UVLO Hysteresis	V_{UVLO3}	-	6.00	-	V	V_{UVLO3}= V_{UVLO1}- V_{UVLO2}
VCC OVP Voltage 1	V_{OVP1}	25.0	27.5	30.0	V	VCC rise
VCC OVP Voltage 2	V_{OVP2}	20.0	22.5	25.0	V	VCC fall
VCC OVP hysteresis	V_{OVP3}	-	5.0	-	V	V_{OVP3}= V_{OVP1}-V_{OVP2}

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●**Electrical Characteristics of control block (Unless otherwise noted, Ta = 25ºC, VCC=12V)**

Parameter	Symbol	Specifications			Unit	Conditions
		MIN	TYP	MAX		
[PWM Type DCDC Driver Block]						
Oscillation Frequency	F_{SW1}	60	65	70	KHz	FB=2.0V Typ frequency
Frequency Hopping Width 1	F_{DEL1}	-	4.0	-	KHz	FB=2.0V
Hopping Fluctuation Frequency	F_{CH}	93	125	157	Hz	
Minimum Pulse Width	T_{min}	-	500	-	ns	
Soft Start Time 1	T_{SS1}	0.75	1.00	1.25	ms	
Soft Start Time 2	T_{SS2}	6.00	8.00	10.00	ms	
Maximum Duty 1	D_{max}	68.0	75.0	82.0	%	During normal operation
Maximum Duty 2	D_{SS1}	5.0	15.0	25.0	%	During soft start 0[ms] to Tss_1[ms]
Maximum Duty 3	D_{SS2}	15.0	25.0	35.0	%	During soft start T_{SS1} [ms] to T_{SS2} [ms]
FB pin Pull-up Resistance	R_{FB}	15	20	25	kΩ	
⊿FB / ⊿CS Rain	Gain	-	5	-	V/V	
FB Burst Voltage	V_{BST}	0.20	0.30	0.40	V	During FB drop
FB OLP Voltage 1a	V_{FOLP1A}	3.3	3.6	3.9	V	When overload is detected (FB rise)
FB OLP Voltage 1b	V_{FOLP1B}	-	V_{FOLP1A}-0.2	-	V	When overload is detected (FB drop)
FB OLP Timer	T_{FOLP}	187	250	312	ms	
[Overcurrent Detection Block]						
Overcurrent Detection Voltage	V_{CS}	0.475	0.500	0.525	V	
Leading Edge Blanking Time	T_{LEB}	-	250	-	ns	
[Output Driver Block]						
OUT pin Pch MOS Ron	R_{POUT}	10	25	39	Ω	
OUT pin Nch MOS Ron	R_{NOUT}	3	7	12	Ω	
[External stop Comparator Block]						
COMP pin stop Detection Voltage	V_{STOP1}	1.8	2.0	2.2	V	Rise
COMP pin stop Detection Voltage	V_{STOP2}	1.6	1.8	2.0	V	Fall
COMP pin stop Detection hysteresis	V_{STOP3}	-	0.2	-	V	$V_{STOP3} = V_{STOP1}-V_{STOP2}$
Mask Time for protection	TSTOP	50	100	200	us	VCCOVP, COMP Mask time

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●Typical Performance Curves

(This is not a guarantee since this is the reference data. Figure 36 shows the measurement circuit diagram.)

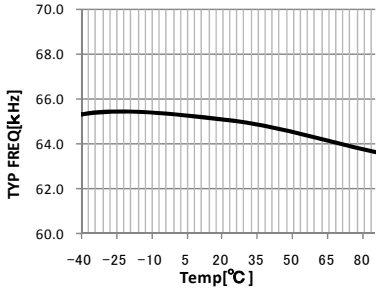


Figure 11, Typ Frequency Fsw1

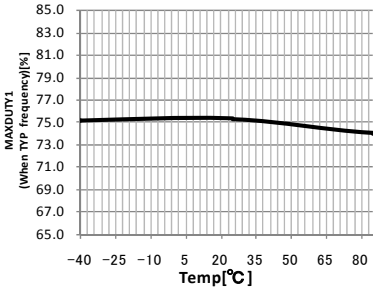


Figure 12, MAXDUTY1 (With Typ frequency)

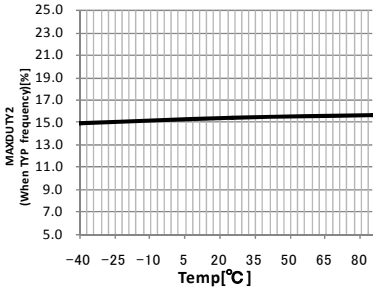


Figure 13, MAXDUTY2 (With Typ frequency)

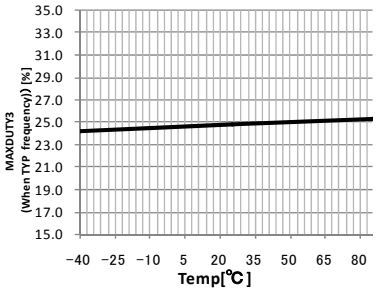


Figure 14, MAXDUTY3 (With Typ frequency)

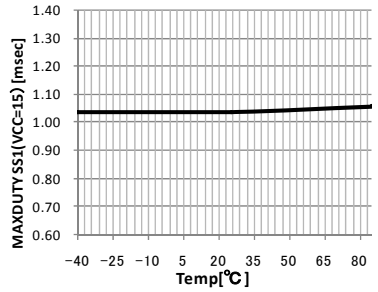


Figure 15, MAXDUTY SS1 (VCC=15)

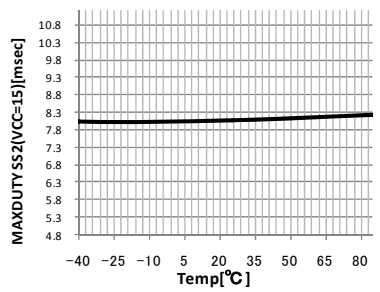


Figure 16, MAXDUTY SS2 (VCC=15)

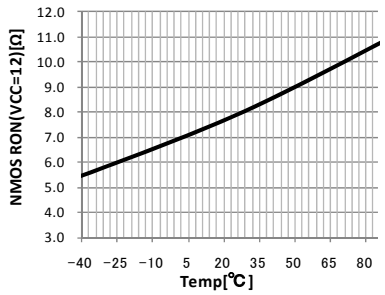


Figure 17, NMOS RON (VCC=12)

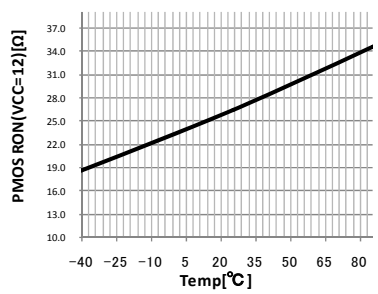


Figure 18, PMOS RON (VCC=12)

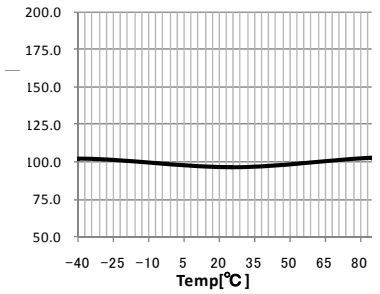


Figure 19, Masking Time

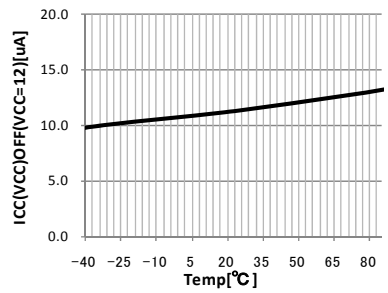


Figure 20, ICC (VCC) OFF (VCC=12)

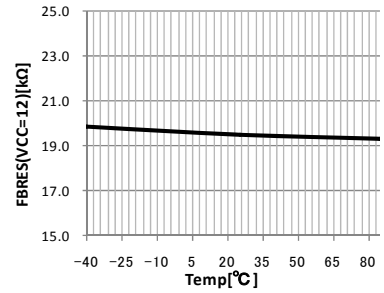


Figure 21, FBRES (VCC=12)

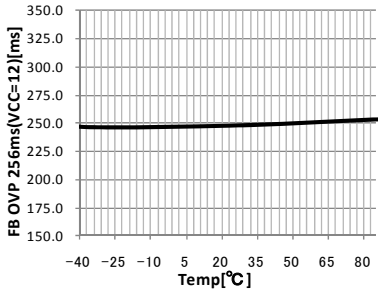


Figure 22, FBOVP Timer (VCC=12)

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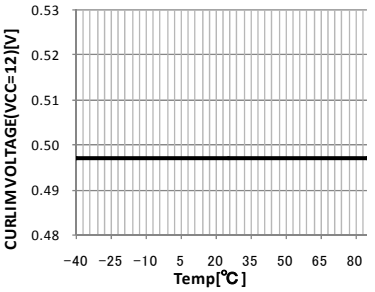


Figure 23, CURLIM Voltage (VCC=12)

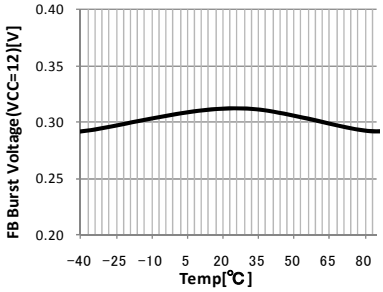


Figure 24, FB Burst Voltage (VCC=12)

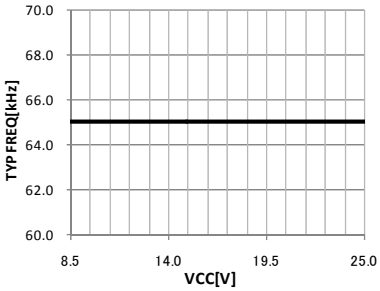


Figure 25, Frequency Fsw1 (temp=25℃)

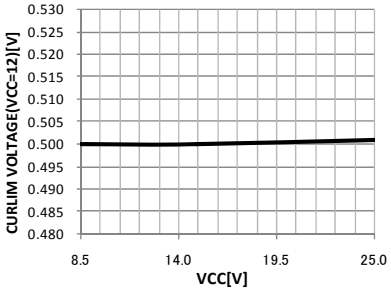


Figure 26, CURLIM Voltage (temp=25℃)

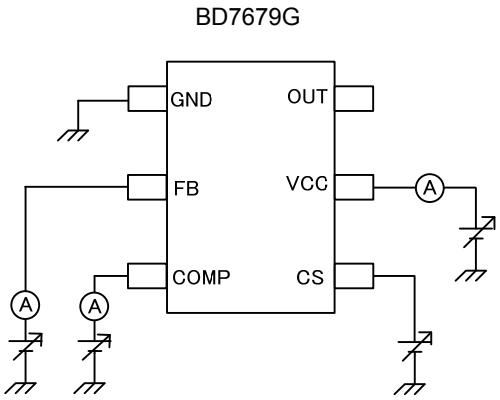


Figure 27, Measurement Circuit Diagram

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●Power Dissipation

The thermal design should set the operation for the following conditions.
(Since the temperature shown below is the guaranteed temperature, be sure to take margin into account.)

1. The ambient temperature Ta must be 85℃ or less.
2. The IC's loss must be within the allowable dissipation Pd.

The thermal reduction characteristics are as follows.
(PCB : 70mm×70mm×1.6mm mounted on glass epoxy substrate)

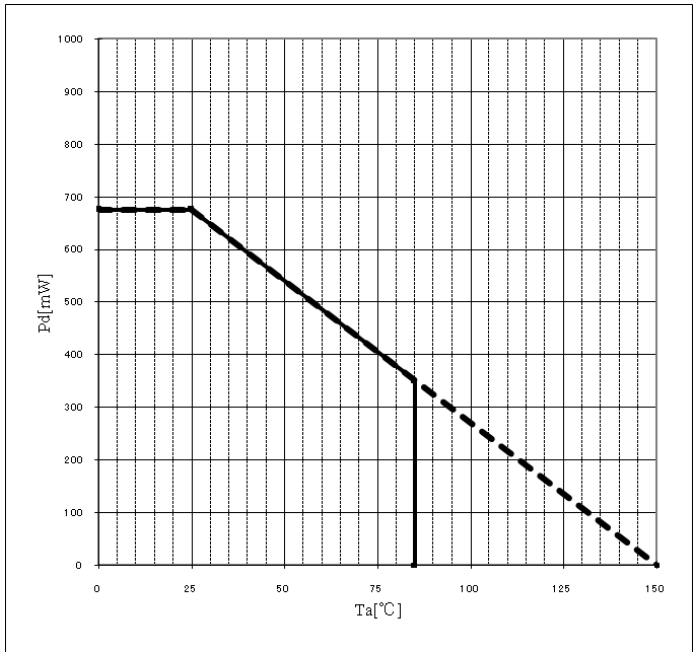


Figure 28, SSOP6 Thermal Reduction Characteristics

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Operational Notes

1. **Reverse Connection of Power Supply**
   Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. **Power Supply Lines**
   Design the PCB layout pattern to provide low impedance supply lines. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. **Ground Voltage**
   Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. **Ground Wiring Pattern**
   When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. **Thermal Consideration**
   Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

6. **Recommended Operating Conditions**
   These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

7. **Inrush Current**
   When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

8. **Operation Under Strong Electromagnetic Field**
   Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

9. **Testing on Application Boards**
   When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

10. **Inter-pin Short and Mounting Errors**
    Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

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Operational Notes – continued

11. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode.
When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

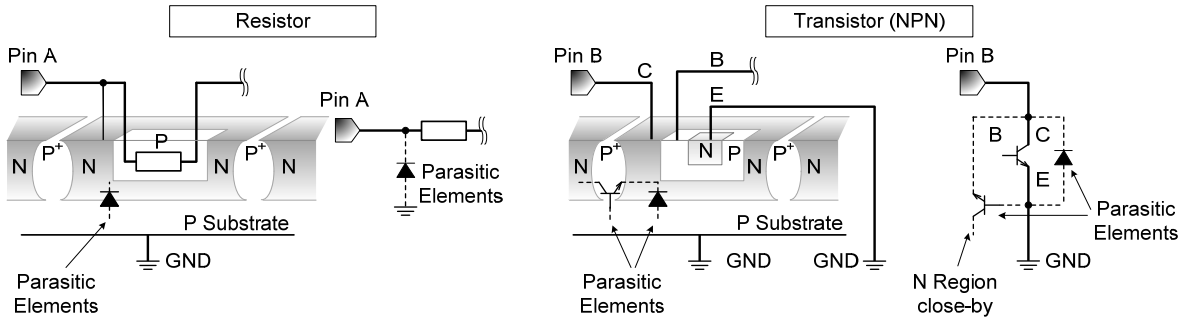


Figure 29. Example of monolithic IC structure

13. Ceramic Capacitor

When using a ceramic capacitor, determine the dielectric constant considering the change of capacitance with temperature and the decrease in nominal capacitance due to DC bias and others.

14. Area of Safe Operation (ASO)

Operate the IC such that the output voltage, output current, and power dissipation are all within the Area of Safe Operation (ASO).

15. Thermal Shutdown Circuit(TSD)

This IC has a built-in thermal shutdown circuit that prevents heat damage to the IC. Normal operation should always be within the IC's power dissipation rating. If however the rating is exceeded for a continued period, the junction temperature (Tj) will rise which will activate the TSD circuit that will turn OFF all output pins. When the Tj falls below the TSD threshold, the circuits are automatically restored to normal operation.
Note that the TSD circuit operates in a situation that exceeds the absolute maximum ratings and therefore, under no circumstances, should the TSD circuit be used in a set design or for any purpose other than protecting the IC from heat damage.

16. Over Current Protection Circuit (OCP)

This IC incorporates an integrated overcurrent protection circuit that is activated when the load is shorted. This protection circuit is effective in preventing damage due to sudden and unexpected incidents. However, the IC should not be used in applications characterized by continuous operation or transitioning of the protection circuit.

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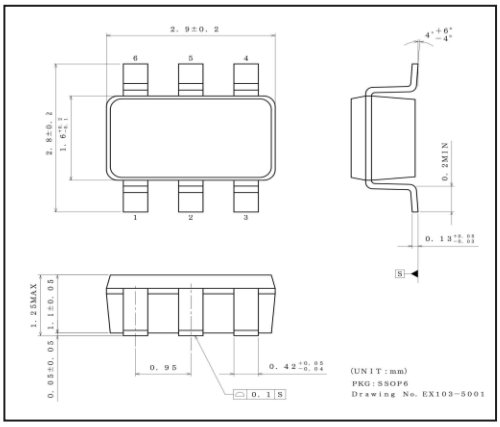
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●Ordering Information

B D 7 6 7 9 G	-	G TR
Part Number		Packaging and forming specification TR: Embossed tape and reel
Package G:SSOP6		

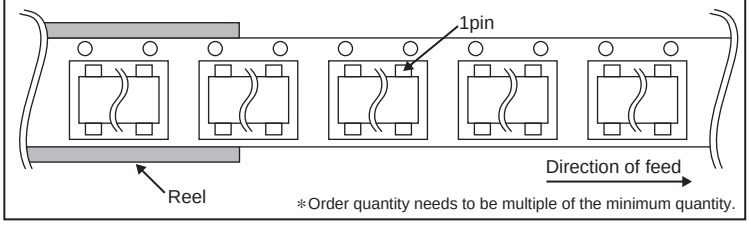
●Physical Dimension Tape and Reel Information

SSOP6



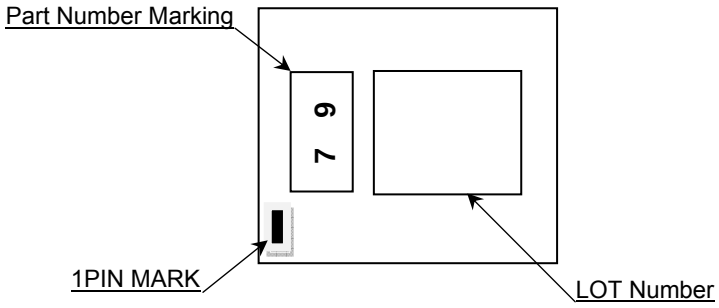
<Tape and Reel information>

Tape	Embossed carrier tape
Quantity	3000pcs
Direction of feed	TR (The direction is the 1pin of product is at the upper right when you hold reel on the left hand and you pull out the tape on the right hand)



∗Order quantity needs to be multiple of the minimum quantity.

●Marking Diagram



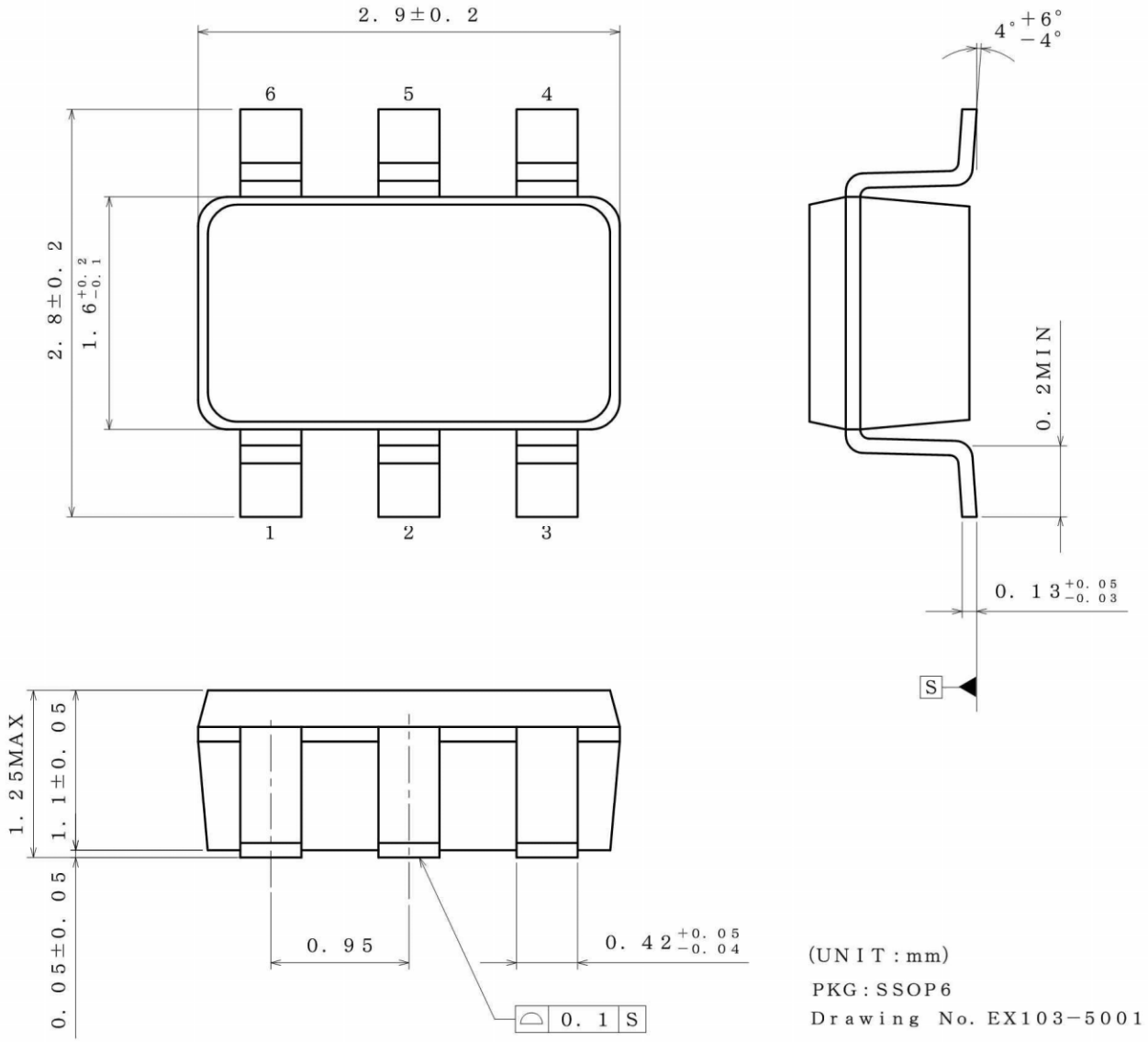
SSOP6 (TOP VIEW)

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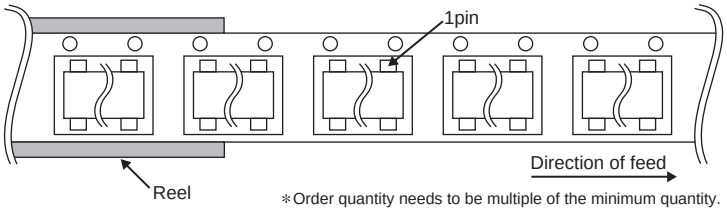
●Physical Dimension, Tape and Reel Information

Package Name	SSOP6



<Tape and Reel information>

Tape	Embossed carrier tape
Quantity	3000pcs
Direction of feed	TR (The direction is the 1pin of product is at the upper right when you hold reel on the left hand and you pull out the tape on the right hand)



∗Order quantity needs to be multiple of the minimum quantity.

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●Revision History

Date	Revision	Changes
2015.4.17	001	New preparation
2015.6.24	002	Modify PIN placement in P-11 Figure27

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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASSⅡb	CLASSⅢ
CLASSⅣ		CLASSⅢ	

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   [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
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   [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
   [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
   [f] Sealing or coating our Products with resin or other coating materials
   [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
   [h] Use of the Products in places subject to dew condensation

4. The Products are not subject to radiation-proof design.

5. Please verify and confirm characteristics of the final or mounted products in using the Products.

6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.

8. Confirm that operation temperature is within the specified range described in the product specification.

9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.

2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

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1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
   - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
   - [b] the temperature or humidity exceeds those recommended by ROHM
   - [c] the Products are exposed to direct sunshine or condensation
   - [d] the Products are exposed to high Electrostatic

2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.

3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.

4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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